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X-1574 US
10/796,471

PATENT
Conf. No.: 2282

IN THE UNITED STATES PATENT OFFICE

Applicant: Leilei Zhang
Assignee: Xilinx, Inc.
Title: "Metal Lid with Improved Adhesion to Package Substrate"
Serial No.: 10/796,471 Filing Date: March 9, 2004
Examiner: Jose R. Diaz Art Unit: 2815
Docket No.: X-1574 US Conf. No.: 2282

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT IN RESPONSE TO THE FINAL OFFICE ACTION AFTER RCE

Dear Sir:

In response to the final Office action after RCE, mailed from the Patent Office on August 27, 2007, please consider the following arguments and reconsider all pending claims.

Listing of the Claims begin on page 2 of this paper.

Amendments to the Drawings begin on page 5 of this paper and includes a replacement sheet.

Remarks begin on page 6 of this paper.